



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/388,826
Filing Date September 1, 1999
Inventor Weimin Li et al.
Assignee Micron Technology, Inc.
Group Art Unit 2813
Examiner E. Kielin
Attorney's Docket No. MI22-1208
Title: Low k Interlevel Dielectric Layer Fabrication Methods

RESPONSE TO September 25, 2001 INTERVIEW SUMMARY

To: Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Bernard Berman (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Sir:

Responsive to the Interview Summary dated September 25, 2001,
Applicant respectfully requests reconsideration of the above-referenced
application in view of the remarks that follow.

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